Amendments to the Claims:

The listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

 (Currently amended) A system for acquiring semiconductor process status information, comprising:

an equipment server for sending a start command according to a first protocol;

a computer system server connected to the equipment server for converting the start command from the first protocol to a second protocol and outputting the converted start command:

a protocol converter connected to the computer system server for converting the start command from the second protocol to a third protocol and outputting the converted command according to the third protocol;

an AD/DA module connected to the protocol converter for converting the start command from the third protocol to an analog signal and outputting the converted command:

an external sensor connected to the AD/DA module for acquiring semiconductor equipment process status information as initiated by the start command;

wherein the AD/DA module converts the semiconductor process status information from the analog signals to the third protocol and outputs the converted information to the protocol converter; the protocol converter converts the semiconductor process status information from the third protocol to the second protocol and outputs the

converted information to the computer system server; and the computer system server outputs the converted information to the equipment server.

- (original) The system as claimed in claim 1, wherein the status information comprises temperature, pressure, flow rate, consistency, rotational speed, voltage value, or electric current value.
- 3. (original) The system as claimed in claim 1, wherein standard voltage value input of the semiconductor process status information are ±15mV, ±50mV, ±100mV, ±150mV, ±500mV, ±1V, ±2.5V, ±5V or ±10V.
- 4. (Currently amended) The system, as claimed in claim 1, wherein standard current input of the semiconductor equipment <u>process</u> status information is 0~20mA or ±4~20mA.
- 5. (Currently amended) The system as claimed in claim 1, wherein standard direct sensor input of the semiconductor <u>process</u> equipment status information is <u>from a</u> thermocouple (J, K, T, E, R, S, B type) or <u>a resistance temperature detector (RTD)RTD (Pt, Ni, Balco)</u>.
- (Currently amended) The system as claimed in claim 1, wherein standard digital input of the semiconductor <u>process</u> equipment status information is high or low (0/1).

(Currently amended) A system for acquiring semiconductor process status information, comprising:

an equipment server for outputting a start command according to a HSMS protocol;

a computer system server connected to the equipment server for converting the start command from the HSMS protocol to a RS232 protocol and outputting the converted command:

a protocol converter connected to the computer system server for converting the start command from the RS232 protocol to a RS485 protocol and outputting the converted command;

an AD/DA module connected to the protocol converter for converting the start command from the RS485 command to an analog signal and outputting the converted command;

an external sensor connected to the AD/DA module for acquiring semiconductor process equipment status information as initiated by the start command;

wherein the AD/DA module converts the semiconductor process status information from the analog signals to the RS485 protocol and outputs the converted information to the protocol converter; the protocol converter converts the semiconductor process status information from the RS485 protocol to the RS232 protocol and outputs the converted information to the computer system server; and the computer system server outputs the semiconductor process status information to the equipment server.

- 8. (original) The system as claimed in claim 7, wherein the status information comprises temperature, pressure, flow rate, consistency, rotational speed, voltage value, or electric current value.
- 9. (original) The system as claimed in claim 7, wherein standard voltage value input of the status information is ±15mV, ±50mV, ±100mV, ±150mV, ±500mV, ±100mV, ±2.5V, ±5V or ±10V.
- (Currently amended) The system, as claimed in claim 7, wherein standard current input of the semiconductor <u>process</u> equipment status information is ±0~20mA or ±4~20mA.
- (Currently amended) The system as claimed in claim 7, wherein standard direct sensor input of the semiconductor <u>process</u> equipment status information is <u>from a</u> thermocouple (J, K, T, E, R, S, B type) or <u>a resistance temperature detector (RTD)RTD (Pt, Ni, Balso)</u>.
- (Currently amended) The system as claimed in claim 7, wherein standard digital input of the semiconductor <u>processequipment</u> status information is high or low (0/1).
- (Currently amended) A method for acquiring semiconductor process status information, comprising the steps of:

a tool application program outputting a start command according to a first-HSMS protocol;

converting the start command from the first-HSMS protocol to a second-RS232 protocol and outputting the converted start command;

converting the start command from the secend-RS232 protocol to a third-RS485 protocol and outputting the converted command according to the RS485third protocol;

converting the start command from the <u>RS485</u>third protocol to an analog signal and outputting the converted command;

activation of an external sensor by the start command;

acquiring semiconductor <u>process</u> equipment status information from the external sensor;

converting the semiconductor process status information <u>from analog signals</u> to the <u>RS485</u>third protocol and outputting the converted information according to the <u>RS485</u>third protocol;

converting the semiconductor process status information from the RS485third protocol to the RS232second protocol and outputting the converted information according to the RS232second protocol;

converting the semiconductor process status information from the <u>RS232</u>second protocol to the <u>first-HSMS</u> protocol; and

outputting the semiconductor process status information to an equipment server according to the HSMSfirst server.

14. (cancelled)

- 15. (original) The method as claimed in claim 13, wherein the status information comprises temperature, pressure, flow rate, consistency, rotational speed, voltage value, or electric current value.
- (original) The method as claimed in claim 13, wherein standard voltage value input of the status information is ±15mV, ±50mV, ±100mV, ±150mV, ±500mV, ±1V, ±2.5V, ±5V or ±10V.
- (Currently amended) The method, as claimed in claim 13, wherein standard current input of the semiconductor <u>process</u> equipment status information is ±0~20mA or ±4~20mA.
- 18. (Currently amended) The method as claimed in claim 13, wherein standard direct sensor input of the semiconductor <u>process</u> equipment status information is <u>from a</u> thermocouple (J, K, T, E, R, S, B type) or <u>a resistance temperature detector</u> (RTD)RTD (Pt, Ni, Balco).
- (Currently amended) The method as claimed in claim 13, wherein standard digital input of the semiconductor <u>process</u> equipment status information is high or low-(0/1).